



# Material Composition Declaration

## EPC2001C

Company Name	Efficient Power Conversion (EPC)	Issue Date:	4/24/2024
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	12.3 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	10.5319	85.9465	88.1231	859465
	Silicon oxide	7631-86-9	0.0361	0.2945		2945
	Silicon nitride	12033-89-5	0.0125	0.1022		1022
	Gallium nitride	25617-97-4	0.0485	0.3958		3958
	Aluminum	7429-90-5	0.0834	0.6805		6805
	Aluminum nitride	24304-00-5	0.0103	0.0843		843
	Titanium	7440-32-6	0.0023	0.0184		184
	Titanium nitride	25583-20-4	0.0092	0.0749		749
	Copper	7440-50-8	0.0014	0.0114		114
	Tungsten	7440-33-7	0.0018	0.0147		147
	Polyimide		0.0613	0.4999	4999	
Under Bump Metal	Titanium	7440-32-6	0.0012	0.0097	0.1056	97
	Copper	7440-50-8	0.0118	0.0960		960
Solder Bump	Copper	7440-50-8	0.1176	0.9597	11.7712	9597
	Nickel	7440-02-0	0.0702	0.5725		5725
	Tin	7440-31-5	1.2321	10.0547		100547
	Silver	7440-22-4	0.0226	0.1843		1843
Sum in total:			12.2540	100.0000	100.0000	1000000

**Note:**

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.